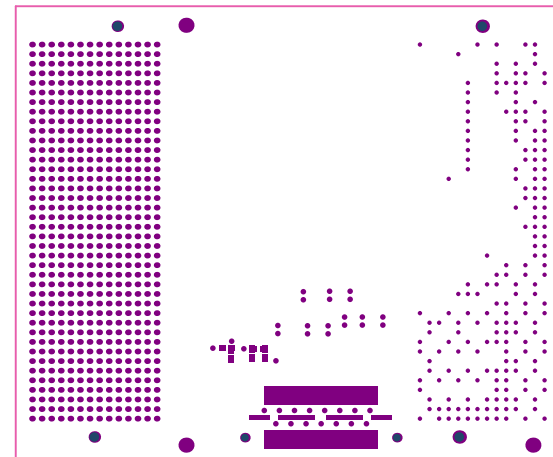
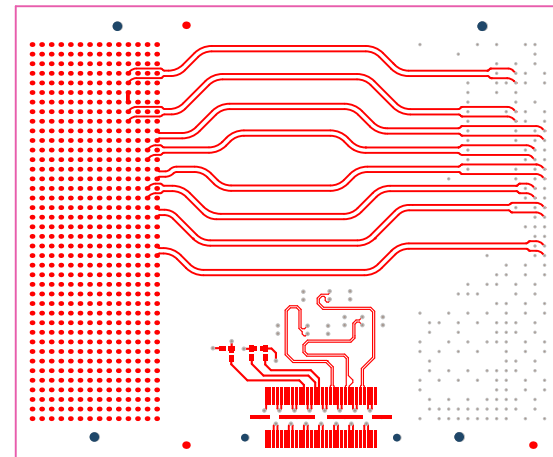


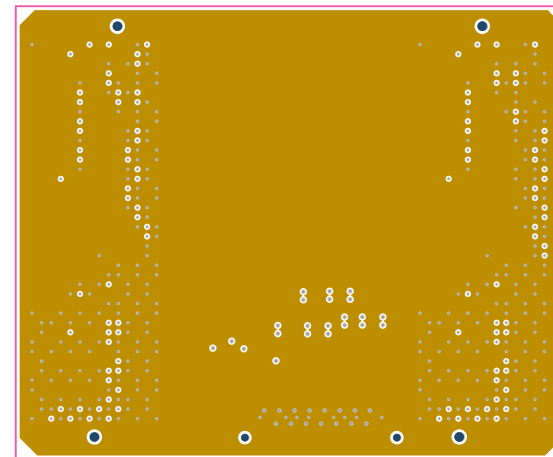
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: FMC+ TO FMC	REV: E2	SUN REV:
LAYER NAME = TOP OVERLAY	TID #: 01021		
PLOT NAME = Top Overlay	GENERATED : 11/09/2017 12:12:36 PM	TEXAS INSTRUMENTS	



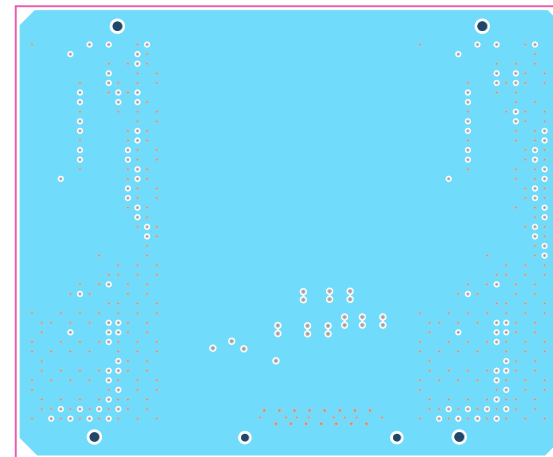
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: FMC+ TO FMC	REV: E2	SUN REV:
LAYER NAME = TOP SOLDER	TID #: 01021		
PLOT NAME = Top Solder Mask	GENERATED : 11/09/2017 12:12:36 PM	TEXAS INSTRUMENTS	



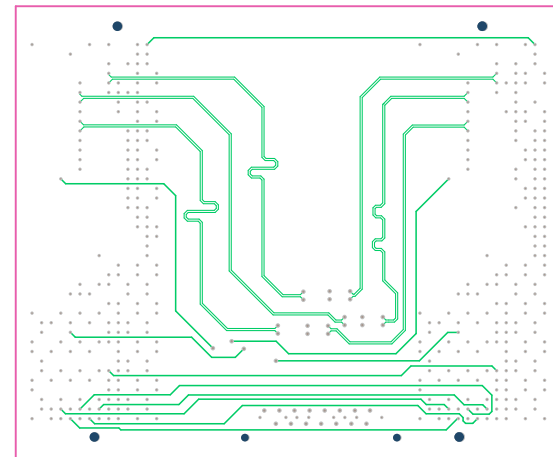
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: FMC+ TO FMC	REV: E2	SUN REV:
LAYER NAME = Top Layer	TID #: 01021		
PLOT NAME = <i>Top Layer</i>	GENERATED : 11/09/2017 12:12:36 PM	TEXAS INSTRUMENTS	



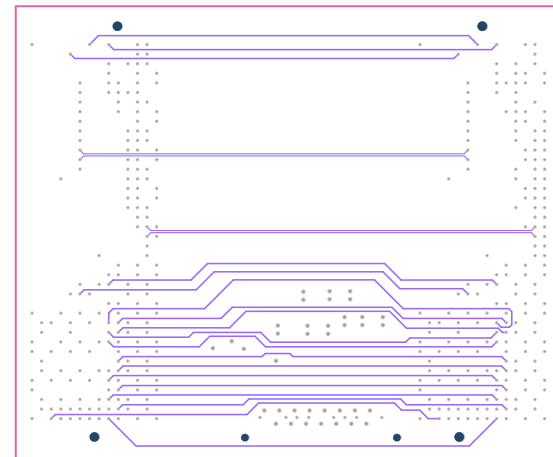
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: FMC+ TO FMC	REV: E2	SUN REV:
LAYER NAME = GND LAYER1	TID #: 01021		
PLOT NAME = Signal Layer 1	GENERATED : 11/09/2017 12:12:36 PM	TEXAS INSTRUMENTS	



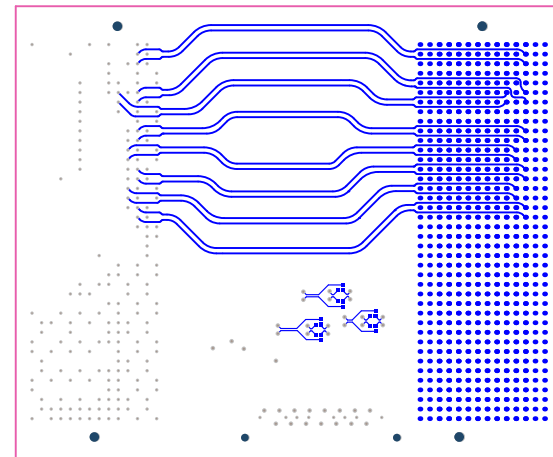
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: FMC+ TO FMC	REV: E2	SUN REV:
LAYER NAME = GND_LAYER2	TID #: 01021		
PLOT NAME = Signal Layer 2	GENERATED : 11/09/2017 12:12:36 PM	TEXAS INSTRUMENTS	



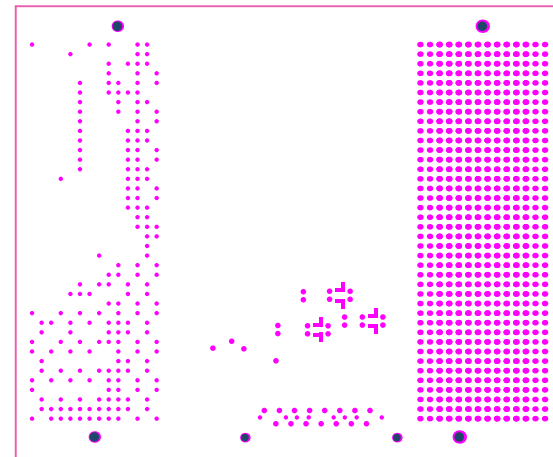
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: FMC+ TO FMC	REV: E2	SUN REV:
LAYER NAME = Signal Layer 1	TID #: 01021		
PLOT NAME = Signal Layer 2	GENERATED : 11/09/2017 12:12:36 PM	TEXAS INSTRUMENTS	



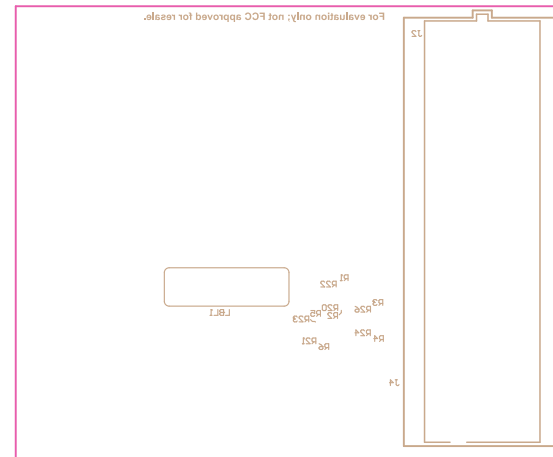
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: FMC+ TO FMC	REV: E2	SUN REV:
LAYER NAME = Signal Layer 2	TID #: 01021		
PLOT NAME = Signal Layer 1	GENERATED : 11/09/2017 12:12:36 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: FMC+ TO FMC	REV: E2	SUN REV:
LAYER NAME = BOTTOM LAYER	TID #: 01021		
PLOT NAME = Bottom Layer	GENERATED : 11/09/2017 12:12:36 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: FMC+ TO FMC	REV: E2	SUN REV:
LAYER NAME = BOTTOM SOLDER	TID #: 01021		
PLOT NAME = <small>Bottom Solder Mask</small>	GENERATED : 11/09/2017 12:12:36 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: FMC+ TO FMC	REV: E2	SUN REV:
LAYER NAME = BOTTOM OVERLAY	TID #: 01021		
PLOT NAME = Bottom Overlay	GENERATED : 11/09/2017 12:12:36 PM	TEXAS INSTRUMENTS	

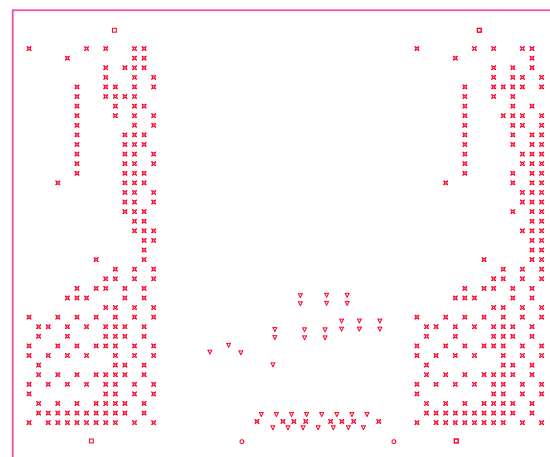
IMPEDANCE TABLE:-

Layer	50 OHM SE TRACE WIDTH (MILS) +/-10%	100 OHM DIFF TIGHTLY COUPLED WIDTH/SPACING (MILS) +/-10%	100 OHM DIFF LOOSELY COUPLED WIDTH/SPACING (MILS) +/-10%	REFERENCE Layer
Top Layer	11mils	6mil trace/ 5mil space	10mil trace/ 18mil space	GND LAYER1
SIGNAL Layer1	8mils	5.5mil trace/ 5.5mil space		GND LAYER1
SIGNAL Layer2	8mils	5.5mil trace/ 5.5mil space		GND LAYER2
BOTTOM Layer	11mils	6mil trace/ 5mil space	10mil trace/ 18mil space	GND LAYER2

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.50mil	3.9	
3	Top Layer	Copper	2.00mil		
4	Dielectric1	R-5670K	5.80mil	3.5	
5	GND LAYER1	Copper	0.60mil		
6	Dielectric 2	R-5775K	5.00mil	3.58	
7	Signal Layer 1	Copper	0.60mil		
8	Dielectric 5	R-5775K	32.80mil	4	
9	Signal Layer 2	Copper	0.60mil		
10	Dielectric 2	R-5775K	5.00mil	3.58	
11	GND LAYER2	Copper	0.60mil		
12	Dielectric 3	R-5670K	5.80mil	3.5	
13	Bottom Layer	Copper	2.00mil		
14	Bottom Solder	Solder Resist	0.50mil	3.9	
15	Bottom Overlay				

Symbol	Count	Hole Size	Plated	Hole Type	Pad Shape
○	2	40.16mil (1.020mm)	NPTH	Round	Rounded
□	6	50.00mil (1.270mm)	NPTH	Round	Rounded
▽	37	12.00mil (0.305mm)	PTH	Round	Rounded
⊗	391	8.00mil (0.203mm)	PTH	Round	Rounded
	436 Total				

FOR 12MIL DRILL +0/-12MIL
FOR 8MIL DRILL +0/-8MIL
FOR NPTH DRILL +/-2MIL



DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
73MM X 60mm

Number of Layers : 6
MIN. TRACK WIDTH: 5.5 MIL
MIN. CLEARANCE: 5 MIL
MIN. VIA PAD SIZE: 18 MIL

MINIMUM ANNULAR RING 5MIL EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:
 FR-408 FR-4 High Tg OTHER R-5775K, R-5670K

THICKNESS: 63 MIL (1.6mm) +/-10% OTHER _____

TOLERANCE: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/- _____

BOW & TWIST: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/- _____

COPPER THICKNESS (FINISHED):
OUTER: 1.2MIL (1oz) 2MIL (1.4oz) 2.8MIL (2oz)
INNER SIGNAL: 0.7MIL (1/2oz) 2.8MIL (2oz) N/A

DRILLING:
REFERENCE: AS SHOWN NC_DRILL FILES
PTH MIN COPPER THICKNESS: 1MIL OTHER _____

BOARD FINISH:
SILKSCREEN: TOP BOTTOM
SILKSCREEN COLOR: WHITE OTHER _____
SOLDER RESIST COLOR:
 GREEN BLUE OTHER _____

SURFACE FINISH: IMMERSION GOLD (ENIG) ENEPIG
 IMM. TIN/SILVER OR EQUIV OTHER _____

ARRAY/PANEL: CUT AND TRIM PER MECH LAYER 1
 N.C. ROUTE V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:
 ANSI IPC-A-600F CLASS -> 1 2 3
 UL 94V-0 RoHS OTHER PER ORDER

ADDITIONAL REQUIREMENTS: VIA TENTING: YES NO
MICROSECTION: YES IMPEDANCE CONTROL: YES NO
BARE BOARD ELEC. TEST: NONE REQUIRED PER ORDER
MANUFACTURER'S UL: RAIL METAL SILK



FMC+ TO FMC

DESIGNED FOR:
Public Release

FILE NAME:
TIDA-01021_FMC+ TO FMC Adapter Card.PcbDoc

ENGINEER:
Ajeet Pal

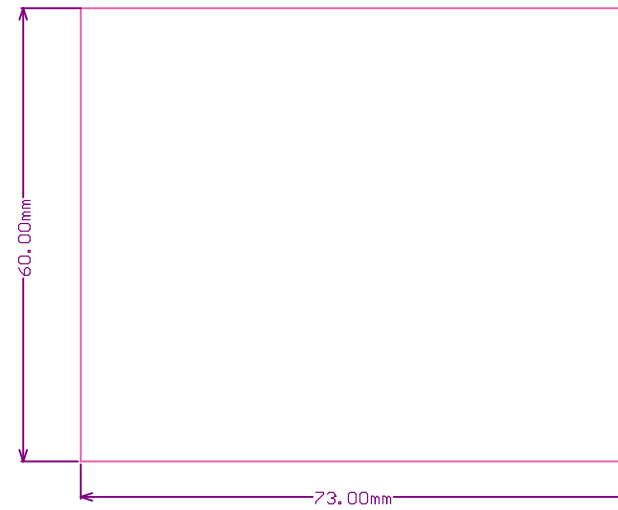
LAYOUT BY:
Avinash N

SCALE: 1,00

ALTIM DESIGNER VERSION:
16.1.9.221

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: FMC+ TO FMC	REV: E2	SUN REV:
LAYER NAME = DRILL DRAWING	TID #: 01021		
PLOT NAME = Drill Drawing	GENERATED : 11/09/2017 12:12:36 PM	TEXAS INSTRUMENTS	

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ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: FMC+ TO FMC	REV: E2	SUN REV:
LAYER NAME = M1 Board Outline	TID #: 01021		
PLOT NAME = Board Dimensions	GENERATED : 11/09/2017 12:12:36 PM	TEXAS INSTRUMENTS	

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